## CRMGGH1005B

#### N-Channel 100V, 4.7mΩ Typ. Power MOSFET

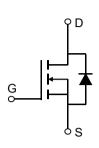
## **Description**

#### **Features**

• 100V, 110A

 $R_{DS(ON)}$  Typ = 4.7m $\Omega$  @  $V_{GS}$  = 10V Advanced Split Gate Trench Technology

- Excellent R<sub>DS(ON)</sub> and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!

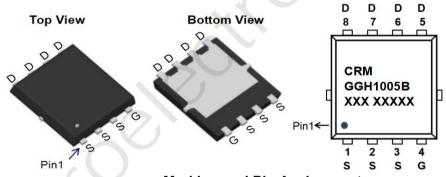




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## **Application**

- Load Switch
- PWM Application
- Power Management



**Marking and Pin Assignment** 

#### **Package Marking and Ordering Information**

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMGGH1005B	CRMGGH1005B	PDFN5x6-8L	TAPING	13"	5000	60000

#### Absolute Maximum Ratings (@ T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
$V_{DS}$	Drain-to-Source Voltage		100	V
V <sub>GS</sub>	Gate-to-Source Voltage		±20	V
_	Continuous Drain Current	T <sub>C</sub> = 25°C	110	А
I <sub>D</sub>	Continuous Diain Current	T <sub>C</sub> = 100°C	66	А
I <sub>DM</sub>	Pulsed Drain Current <sup>(1)</sup>		440	А
E <sub>AS</sub>	Single Pulsed Avalanche Energy <sup>(2)</sup>		196	mJ
$P_{D}$	Power Dissipation	T <sub>C</sub> = 25°C	125	W
$R_{ heta JC}$	Thermal Resistance, Junction to Case		1	°C/W
$T_{J}, T_{STG}$	Junction & Storage Temperature Range		-55 to 150	°C

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### **Electrical Characteristics** (T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Chara	acteristics					
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V	-	-	1.0	μΑ
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				6	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.4	2.7	3.6	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	$V_{GS} = 10V, I_D = 30A$	-	4.7	6.1	mΩ
Dynamic	Characteristics					
C <sub>iss</sub>	Input Capacitance		- /	2113	-	pF
$C_{oss}$	Output Capacitance	$V_{GS} = 0V, V_{DS} = 50V,$ f = 1MHz	-	812	-	pF
$C_{rss}$	Reverse Transfer Capacitance	I – IIVINZ	X -\	14	-	pF
$Q_g$	Total Gate Charge		7	35	-	nC
$Q_{gs}$	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 50V, I_{D} = 20A$	<b>U</b> .	8.2	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge	V <sub>DS</sub> - 30V, I <sub>D</sub> - 20A	-	9.5	-	nC
Switchin	g Characteristics					
t <sub>d(on)</sub>	Turn-On DelayTime		-	13.5	-	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 50V$	-	32	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	$I_D$ = 20A, $R_{GEN}$ = $6\Omega$	-	42	-	ns
$t_{f}$	Turn-Off Fall Time		-	48	-	ns
Drain-So	urce Diode Characteristics and M	Max Ratings				
Is	Maximum Continuous Drain to Source Diode Forward Current		-	-	110	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	440	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	1 454 1711 40047	-	52	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 15A$ , di/dt = 100A/us	-	65	-	nC

Notes:

<sup>1.</sup> Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

<sup>2.</sup>  $E_{AS}$  condition: Starting  $T_J$ =25°C,  $V_{DD}$ =50V,  $V_G$ =10V,  $R_G$ =25ohm, L=0.5mH,  $I_{AS}$ =28A

<sup>3.</sup> Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.

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### **Test Circuit**

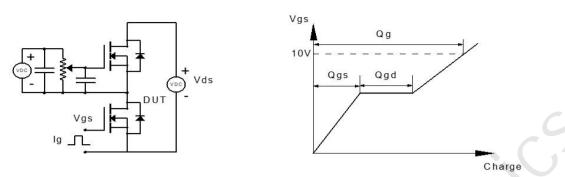


Figure 1: Gate Charge Test Circuit & Waveform

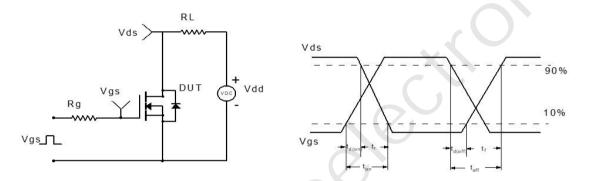


Figure 2: Resistive Switching Test Circuit & Waveform

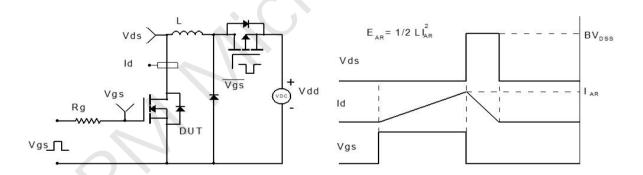


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

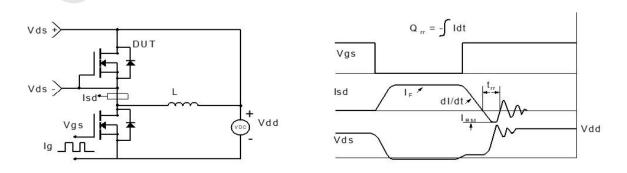
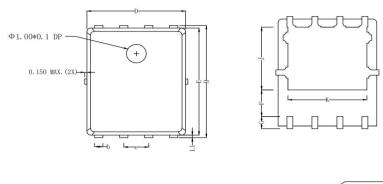


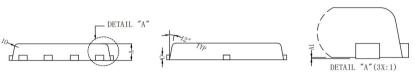
Figure 4: Diode Recovery Test Circuit & Waveform

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## Package Mechanical Data(PDFN5x6-8L)





Dimensions In Millimeterer					
Symbol	MIN	TYP	MAX		
A	0.90	1.00	1.10		
A1	0.00	0.03	0.05		
b	0. 25	0.30	0.35		
С	0. 254 REF				
D	4.80	4. 90	5.00		
F	1.35 REF				
Е	5. 65	5. 75	5. 85		
e	1. 27 BSC				
Н	5. 90	6.00	6.10		
L1	0.10	0.13	0.16		
G	0.55 REF				
K	4.00 REF				
J	3.45 REF				

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### **Contact information**

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